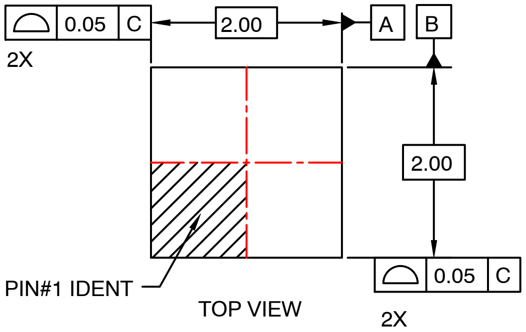
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

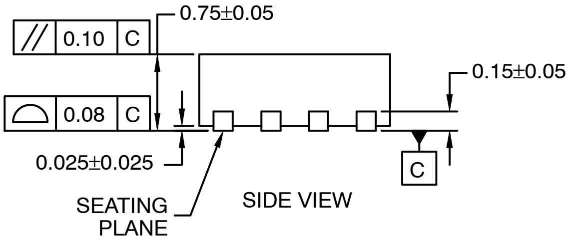
ON Semiconductor®

WDFN8 2x2, 0.5P
CASE 511DL
ISSUE O

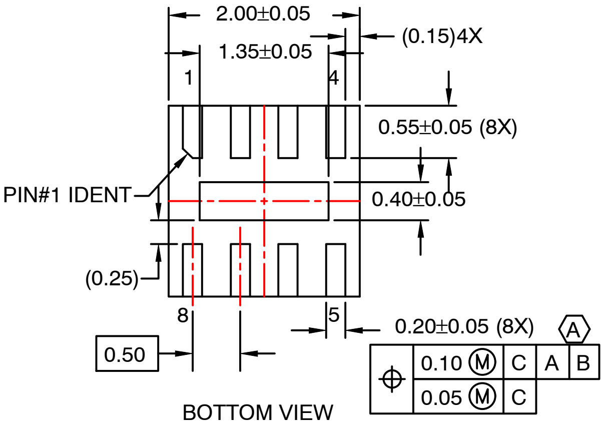
DATE 31 JUL 2016



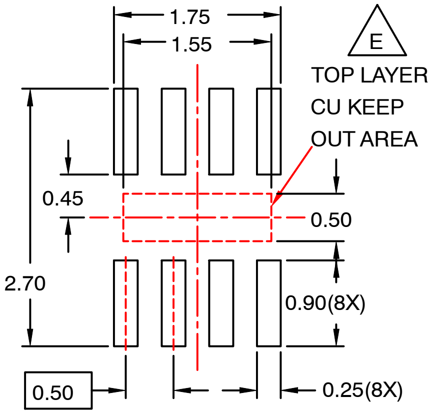
TOP VIEW



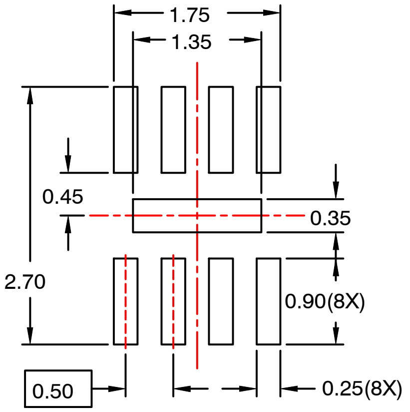
SIDE VIEW



BOTTOM VIEW



OPTION #1: NO CENTER PAD



OPTION #2: WITH CENTER PAD

RECOMMENDED LAND PATTERN

(NSMD PAD TYPE)

NOTES:

A. PACKAGE CONFORMS TO JEDEC MO−229, VARIATION WCCE EXCEPT WHERE NOTED.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
E. IF CENTER PAD IS NOT SOLDERED TO, NO EXPOSED METAL IS ALLOWED IN THE TOP LAYER OF THE BOARD IN THE AREA SHOWN.

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